

a coil embedded in an outer molding, said coil being constructed by winding a conducting wire onto said bobbin,

a high-temperature metallic solder layer coated on said conducting wire; and

a protective layer coated on said high-temperature metallic solder layer;

wherein said protective layer is an electrically-insulating material resistant to permeation by sulfur compounds; and

wherein said high-temperature metallic solder layer suppresses reduction in adhesive strength between the protective layer and the conducting wire, wire breakage, and short circuiting between said conducting wires.

6. (Amended) The electromagnetic device according to Claim 5, wherein said electrically-insulating material resistant to permeation by sulfur compounds is a thermosetting resin.

Please add the following new claims:

7. (New) The electromagnetic device according to claim 5, wherein the high-temperature metallic solder layer comprises a tin-lead solder.

8. (New) The electromagnetic device according to claim 5, wherein the high-temperature metallic solder layer consists of a tin-lead solder, wherein a weight percentage of lead in said tin-lead solder is 90 wt% or more.

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9. (New) The electromagnetic device according to claim 5, wherein the high-temperature metallic solder layer consists of a tin-lead solder, wherein a weight percentage of lead in said tin-lead solder is 60 wt% or more.